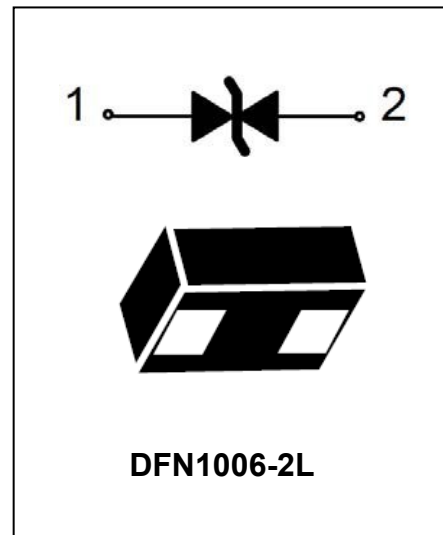


Features

- ◆ 150 Watts peak pulse power ($t_p = 8/20\mu s$)
- ◆ Transient protection for high speed data lines to
IEC 61000-4-2 (ESD) $\pm 15kV$ (air), $\pm 8kV$ (contact)
IEC 61000-4-4 (EFT) 40A (5/50ns)
IEC 61000-4-5 (Surge) 5(8/20 μs)
- ◆ Small Body Outline Dimensions: 0.039" * 0.024"
(1.0 mm x 0.60 mm)
- ◆ Stand-off Voltage: 5.0V
- ◆ Response Time is Typically < 1 ns



Applications

- ◆ 10/100/1000 Mbits/s Ethernet
- ◆ FireWire
- ◆ Display ports
- ◆ MDDI ports
- ◆ Digital Visual Interface (DVI)
- ◆ Cellular handsets & accessories
- ◆ Computer and peripherals

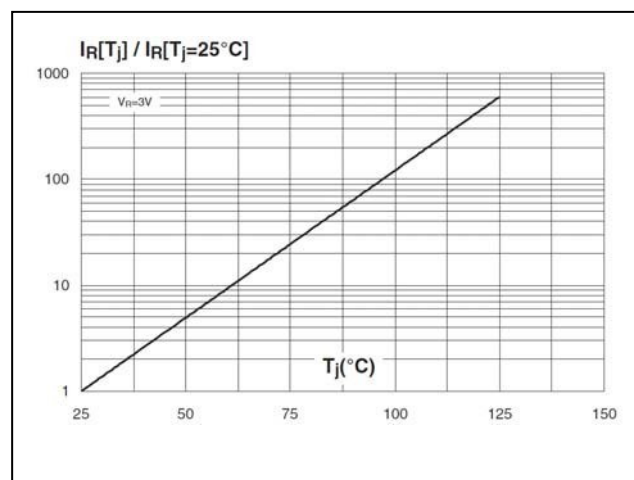
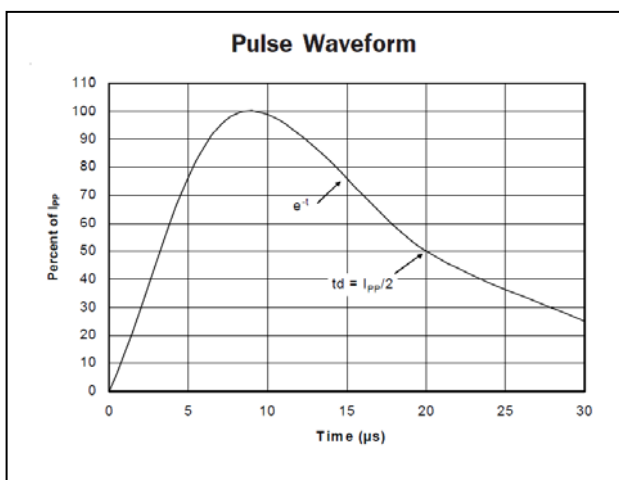
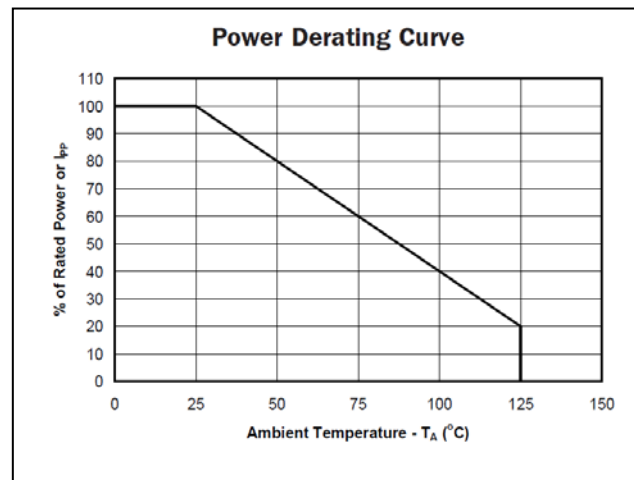
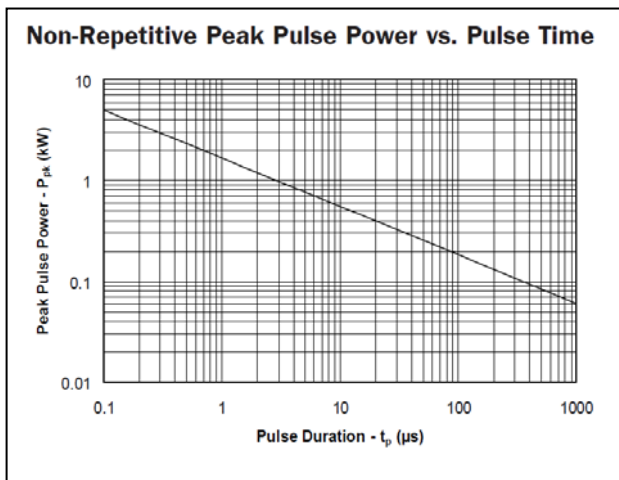
Maximum Rating @ $T_a = 25^\circ C$ unless otherwise specified

Symbol	Parameter		Ratings	Units
ESD	IEC 61000-4-2 (HBM-ESD)	Contact	8	KV
		Air	15	
T_L	Lead Soldering Temperature		260(10sec.)	$^\circ C$
T_J	Operating Temperature		-55 to +125	$^\circ C$
T_{STG}	Storage Temperature		-55 to +150	$^\circ C$

Electrical Characteristics@ Ta=25°C unless otherwise

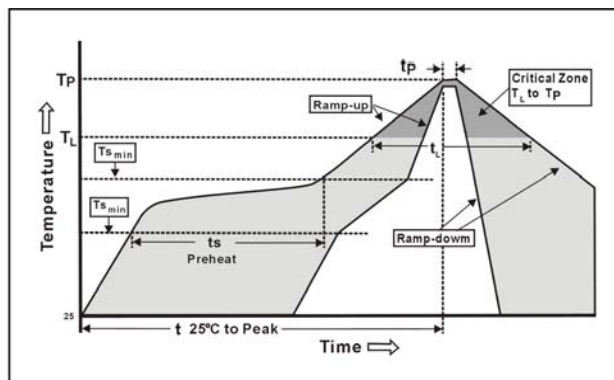
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V_{RWM}	Reverse Working Voltage				5	V
V_{BR}	Reverse Breakdown Voltage	$I_T = 1mA$,	5.5		7.6	V
I_R	Reverse Leakage Current	$V_{RWM} = 5V$			1	μA
V_C	Clamping Voltage	$I_{PP} = 1A$, $t_p = 8/20\mu s$			9.8	V
		$I_{PP} = 8A$, $t_p = 8/20\mu s$			15	V
R_{DYN}	Dynamic resistance			0.2		Ω
C_J	Junction Capacitance	$V_R = 0V$, $f = 1MHz$			15	pF

Typical Characteristics@ Ta=25°C unless otherwise specified



Soldering Parameters

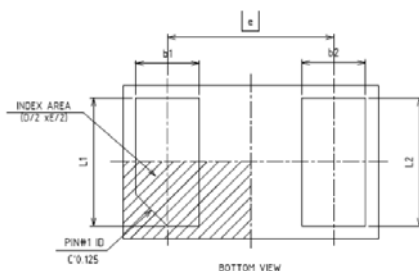
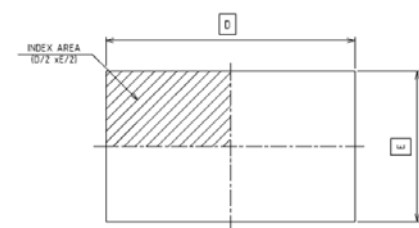
Reflow Condition		Fb – Free assembly
Pre Heat	- Temperature Min ($T_{s(\text{Min})}$)	150°C
	- Temperature Max ($T_{s(\text{Max})}$)	200°C
	- Time (Min to max) (t_p)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second Max
$T_{s(\text{Max})}$ to T_L - Ramp-up Rate		3°C/second Max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		250 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second Max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



Package Outline

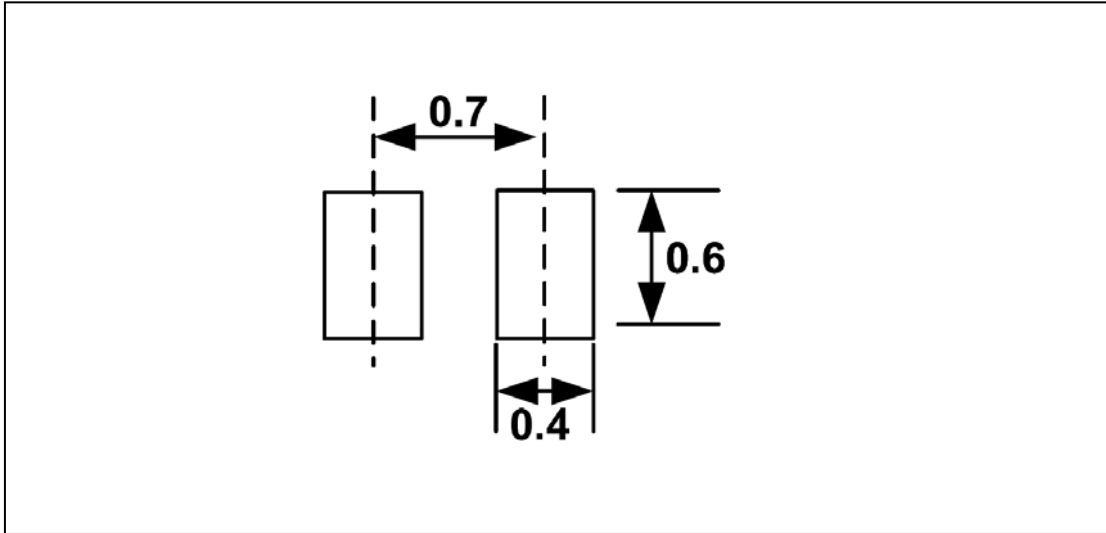
Plastic surface mounted package

DFN 1006-2L



Symbol	Dimensions in mm		
	Min	Nom	Max
A	0.450	0.500	0.550
A1	0.000	0.002	0.050
D	0.950	1.000	1.050
E	0.550	0.600	0.650
e		0.650	
b1	0.200	0.250	0.300
b2	0.200	0.250	0.300
L1	0.450	0.500	0.550
L2	0.450	0.500	0.550

Soldering Footprint



Package And Marking Information

Device	Package	Shipping	Reel Size
ZX0511P	DFN1006-2L	10K/Reel	7 inch